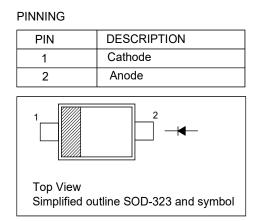
Silicon Epitaxial Planar Switching Diode

Features

- Small plastic package suitable for surface mounted design
- High reliability with high surge current handling capability



Applications

High speed switching

Absolute Maximum Ratings (T_a = 25°C)

Parameter	Symbol	Value	Unit	
Peak Reverse Voltage	V _{RM}	90	V	
Reverse Voltage	VR	80	V	
Average Rectified Forward Current	I _{F(AV)}	100	mA	
Peak Forward Current	IFM	225	mA	
Surge Forward Current (1 s)	IFSM	500	mA	
Power Dissipation	Ptot	200	mW	
Junction Temperature	Tj	150	°C	
Storage Temperature Range	T _{stg}	- 55 to + 150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	R _{θJA}	625	°C/W

¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Electrical Characteristics (T_a = 25°C)

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I _R = 100 μA	V(BR)R	80	-	V
Forward Voltage at I _F = 100 mA	VF	-	1.2	V
Reverse Current at V _R = 80 V	IR	-	0.1	μA
Capacitance between Terminals at $V_R = 0.5 V$, f = 1 MHz	Ст	-	3	pF
Reverse Recovery Time at I _F = 10 mA, I _{II} = 0.1 X I _R , V _R = 6 V, R _L = 100 Ω	t _{rr}	-	4	ns



Electrical Characteristics Curves

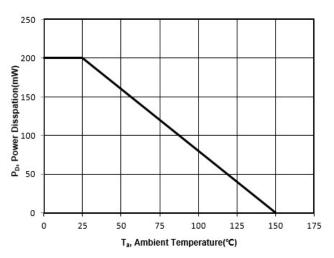


Fig 1. Power Derating Curve

Fig 2. Total Capacitance vs. Reverse Voltage

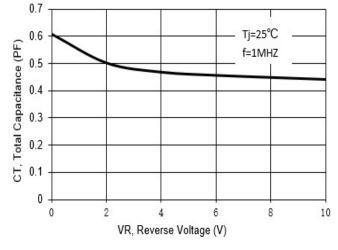


Fig 3. Reverse Current vs. Reverse Voltage

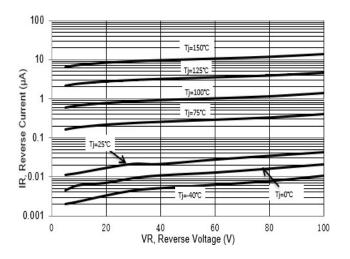
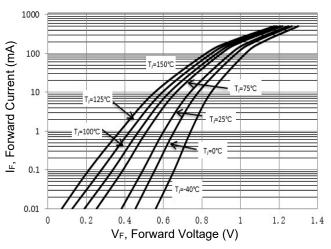


Fig 4. Forward Characteristics

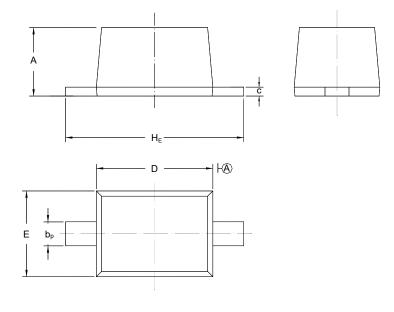




PACKAGE OUTLINE

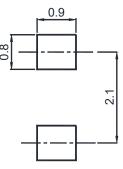
Plastic surface mounted package; 2 leads

SOD-323



UNIT	А	bp	С	D	Е	HE
mm	1.10	0.40	0.15	1.80	1.35	2.80
	0.80	0.25	0.10	1.60	1.15	2.30

Recommended Soldering Footprint



Packing information

	Paakaga	Tape Width	Pitch		Reel Size		Por Pool Pooking Quantity	
Package	(mm)	mm	inch	mm	inch	Per Reel Packing Quantity		
	SOD-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000	

Marking information

" W2 " = Part No.			ľ
" III " = Cathode line Font type: Arial		W2	

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